

/ Descriptions

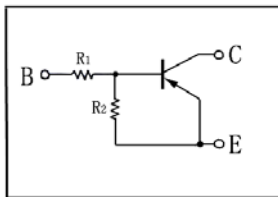
SOT-23 PNP Silicon PNP Digital transistor in a SOT-23 Plastic Package.

/ Features

With built-in bias resistors, simplify circuit design, reduce a quantity of parts and manufacturing process.

/ Applications

Switching, inverter circuit, interface circuit and driver circuit applications.

/ Equivalent Circuit**/ Pinning**

PIN 1 Base PIN 2 Emitter PIN 3 Collector

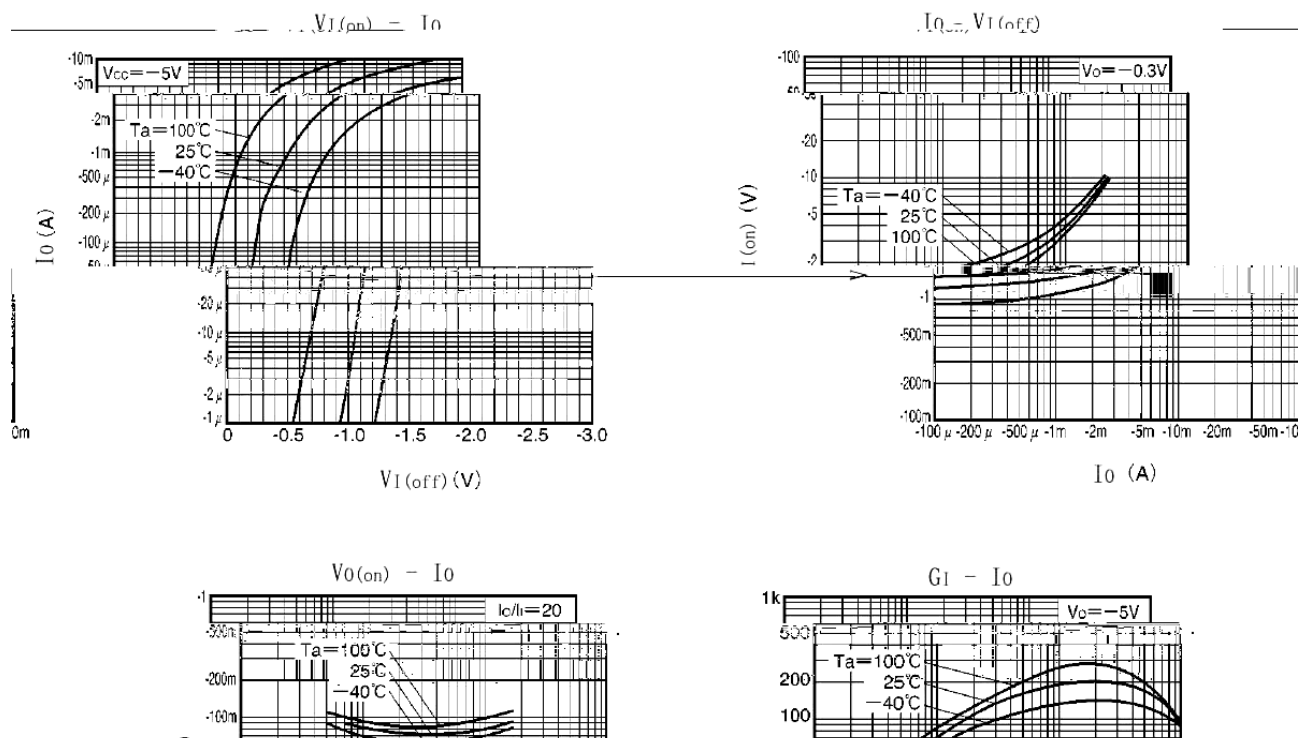
/ h_{FE} Classifications & Marking

Marking	H16
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Parameter	Symbol	Rating	Unit
Output Voltage	V_{CC}	-50	V
Input Voltage	V_{IN}	-40	V
		10	V
Output Current	$I_{C\ max}$	-100	mA
	I_O	-30	mA
Power Dissipation	P_d	200	mW
Junction Temperature	T_j	150	°C
Storage Temperature Range	T_{stg}	-55 150	°C

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Input Voltage	$V_{I(off)}$	$V_{CC}=-5.0V$ $I_O=-100\mu A$			-0.5	V
	$V_{I(on)}$	$V_O=-0.3V$ $I_O=-2.0mA$	-3.0			V

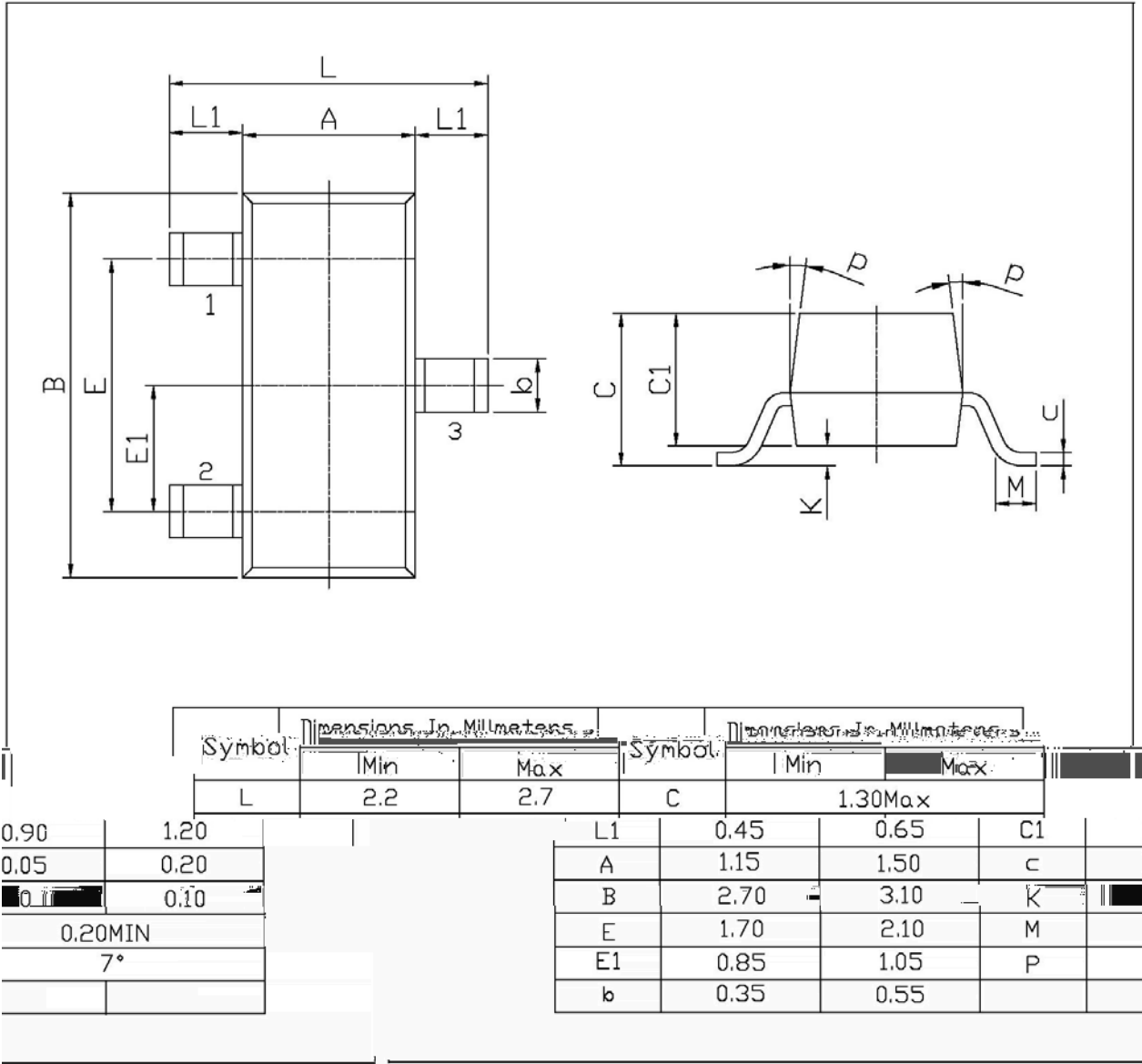
/ Electrical Characteristic Curve



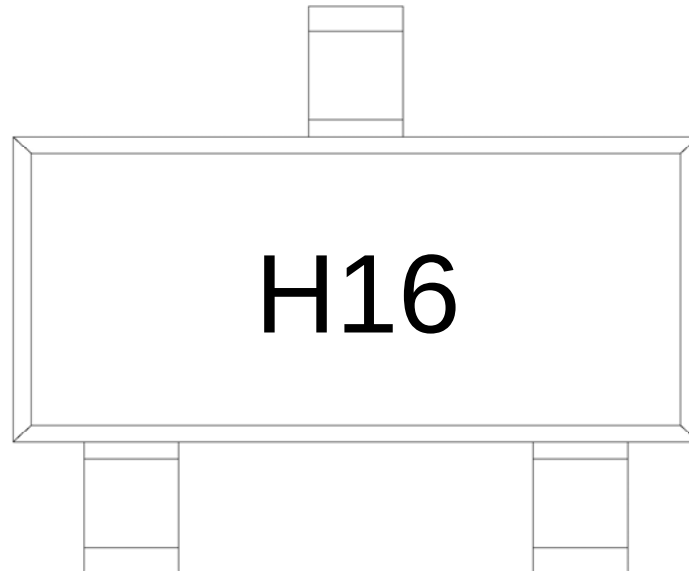
/ Package Dimensions

SOT-23

单位：mm



/ Marking Instructions



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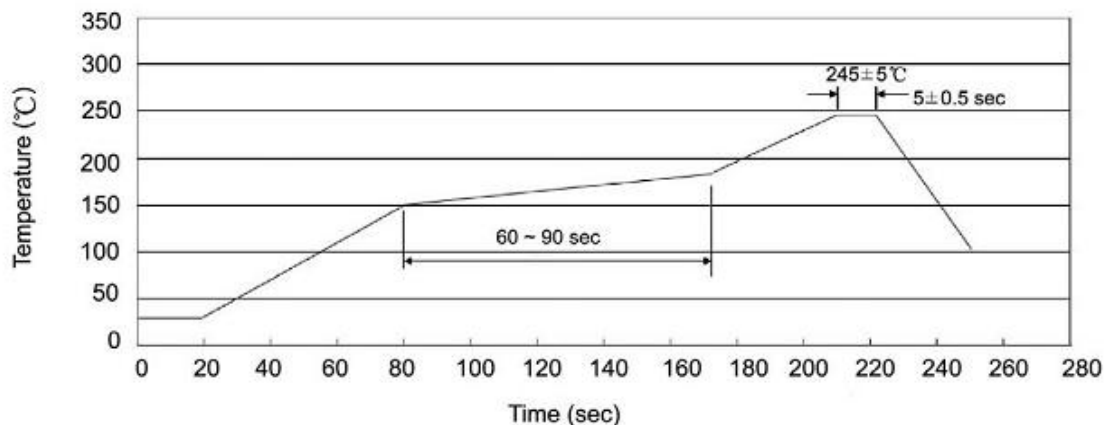
16

Note:

H Company Code

16 Product Type Code

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5℃ Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm ³)		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SOT-23	3,000	10	30,000	6	180,000	7 ×8	180×120×180	390×385×205

/ Notices